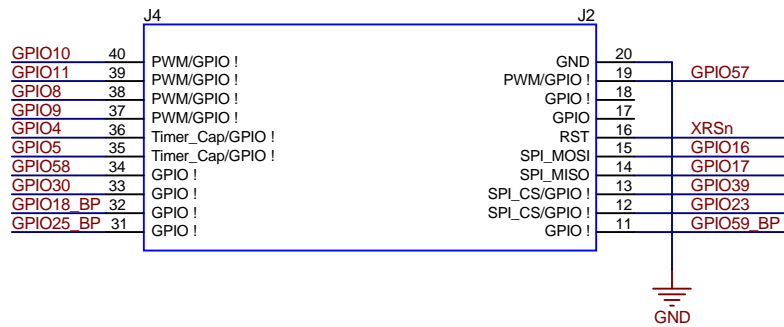
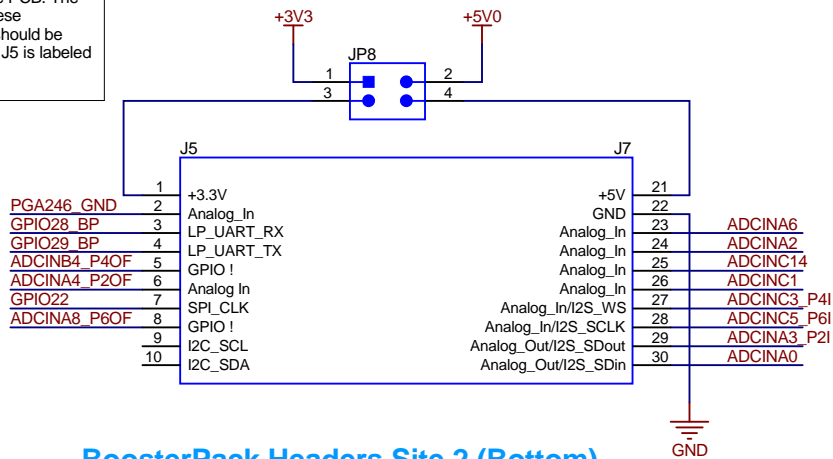


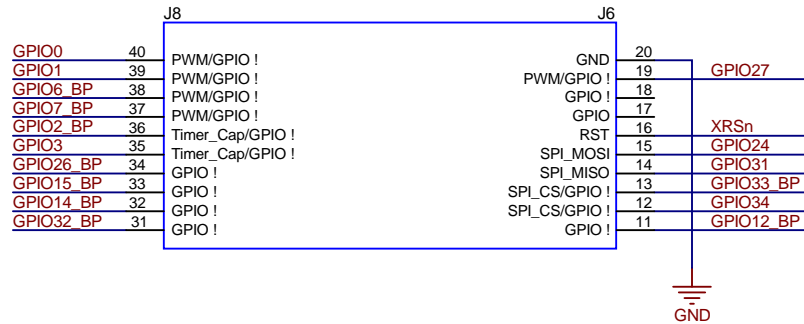
BoosterPack Headers Site 1 (Top)



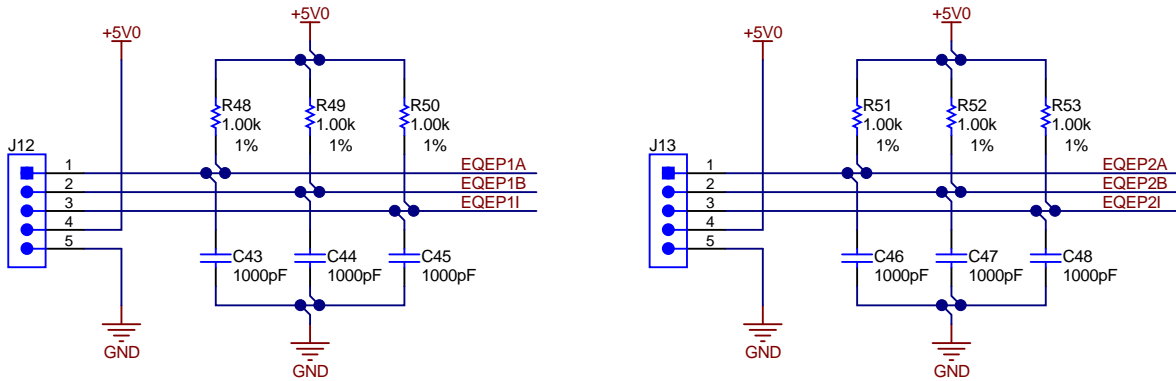
J5 - J8 are labeled on the PCB. The Pin numbers listed on these schematic components should be offset by 40. i.e. pin 1 on J5 is labeled as pin 40 on the PCB.



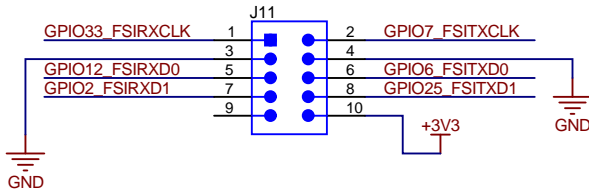
BoosterPack Headers Site 2 (Bottom)



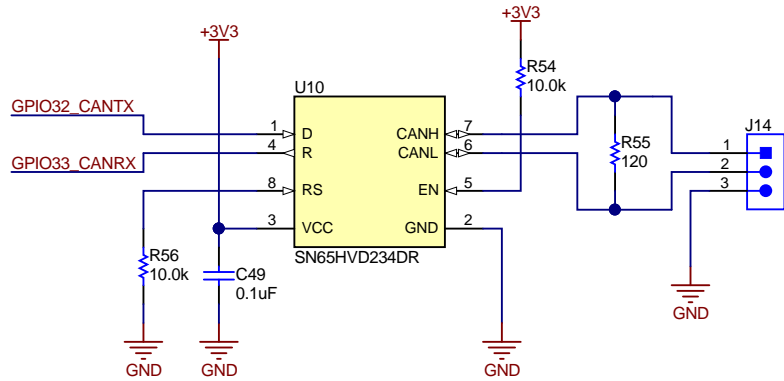
EQEP Connectors



FSI Connector

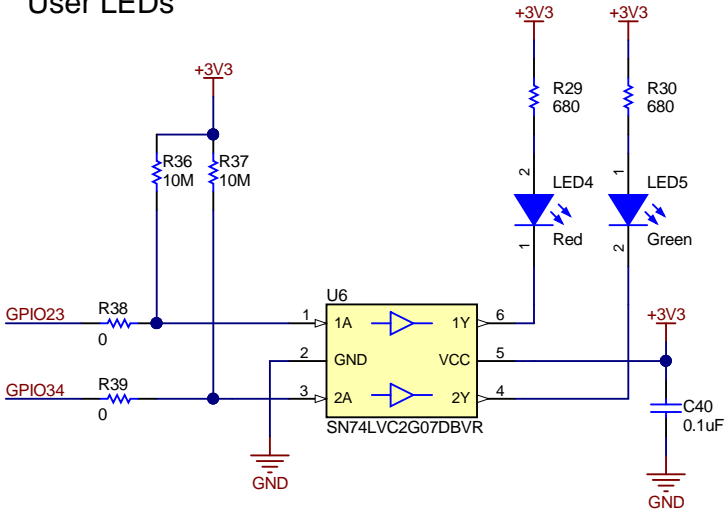


CAN Connector

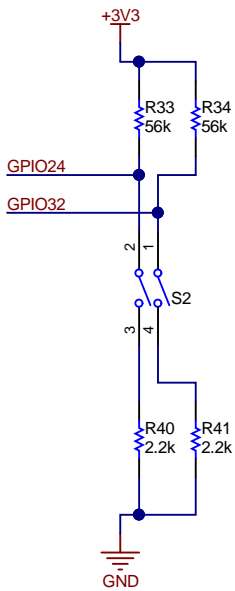


Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

User LEDs



Boot Mode Select

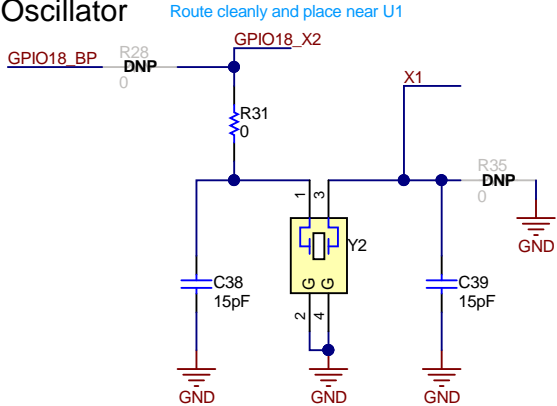


Selected Boot Mode Chart

S2 placed upside-down (so UP is open (1), DOWN is closed (0))

Mode #	GPIO24	GPIO32	Boot Mode
00	0	0	Boot from Parallel GPIO
01	0	1	Boot from SCI / Wait Mode
02	1	0	Boot from CAN
03	1	1	Boot from Flash

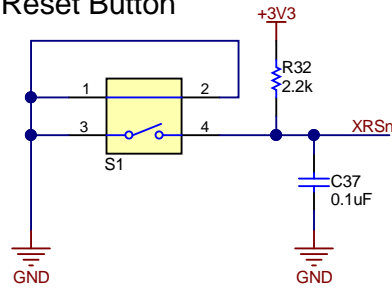
Oscillator



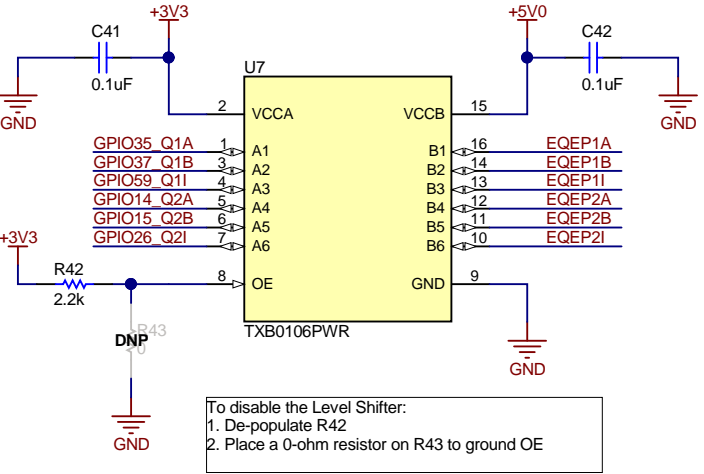
By default:
- Crystal Y2 is connected between X1 and X2.
- GPIO18_BP is not connected to the BoosterPack header.

If GPIO18 is needed at the Boosterpack Headers:
- Remove R35
- Place 0ohm resistors on both R31 and R28

Reset Button

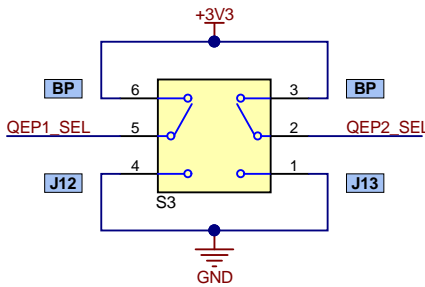
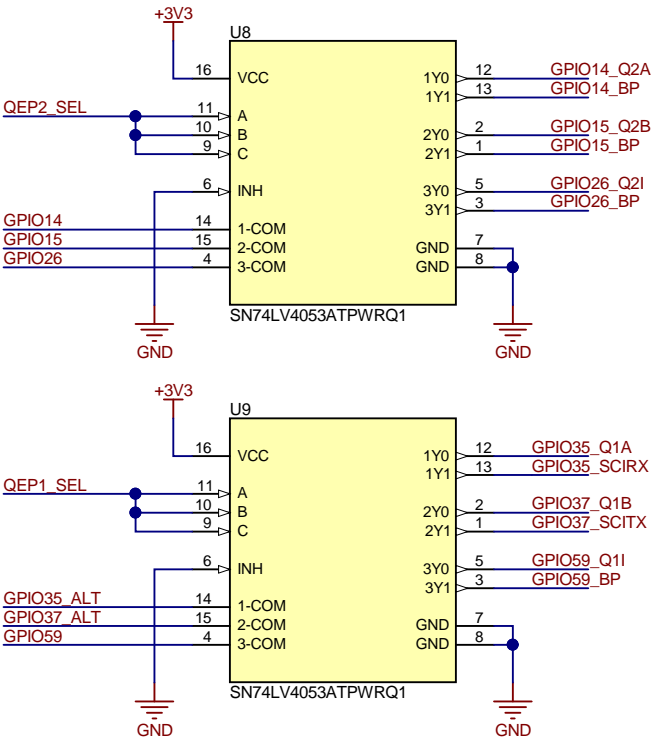


EQEP Level Shifter



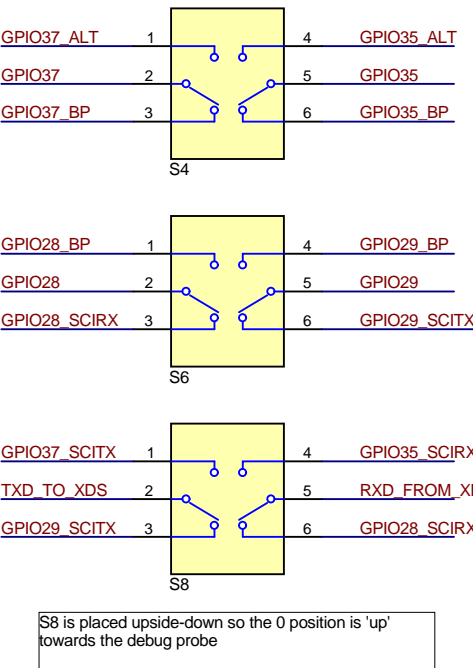
To disable the Level Shifter:
1. De-populate R42
2. Place a 0-ohm resistor on R43 to ground OE

EQEP Routing

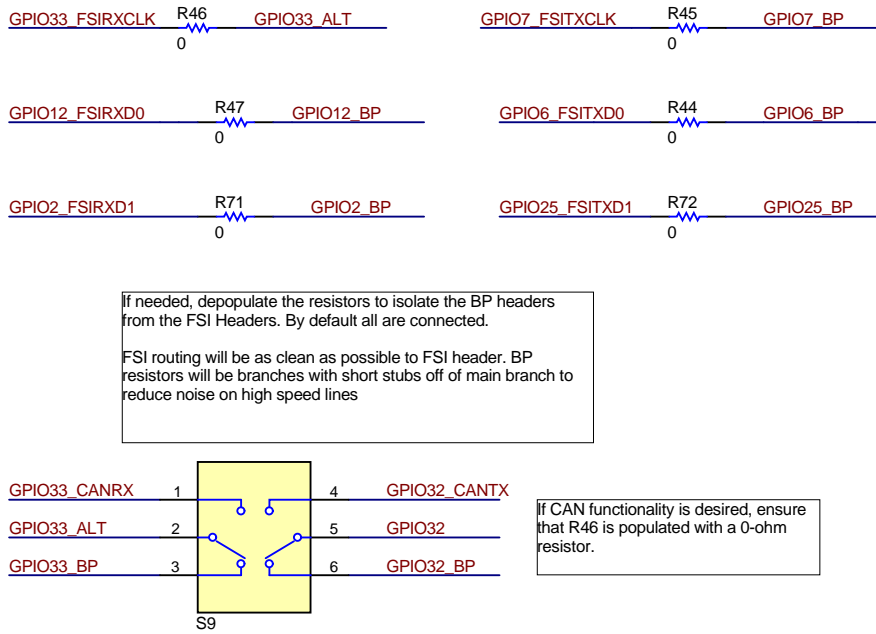


S3 (1, UP): QEP signals are routed to the BoosterPack Headers (default)
S3 (0, DOWN): QEP signals are routed to the QEP Headers

UART Routing



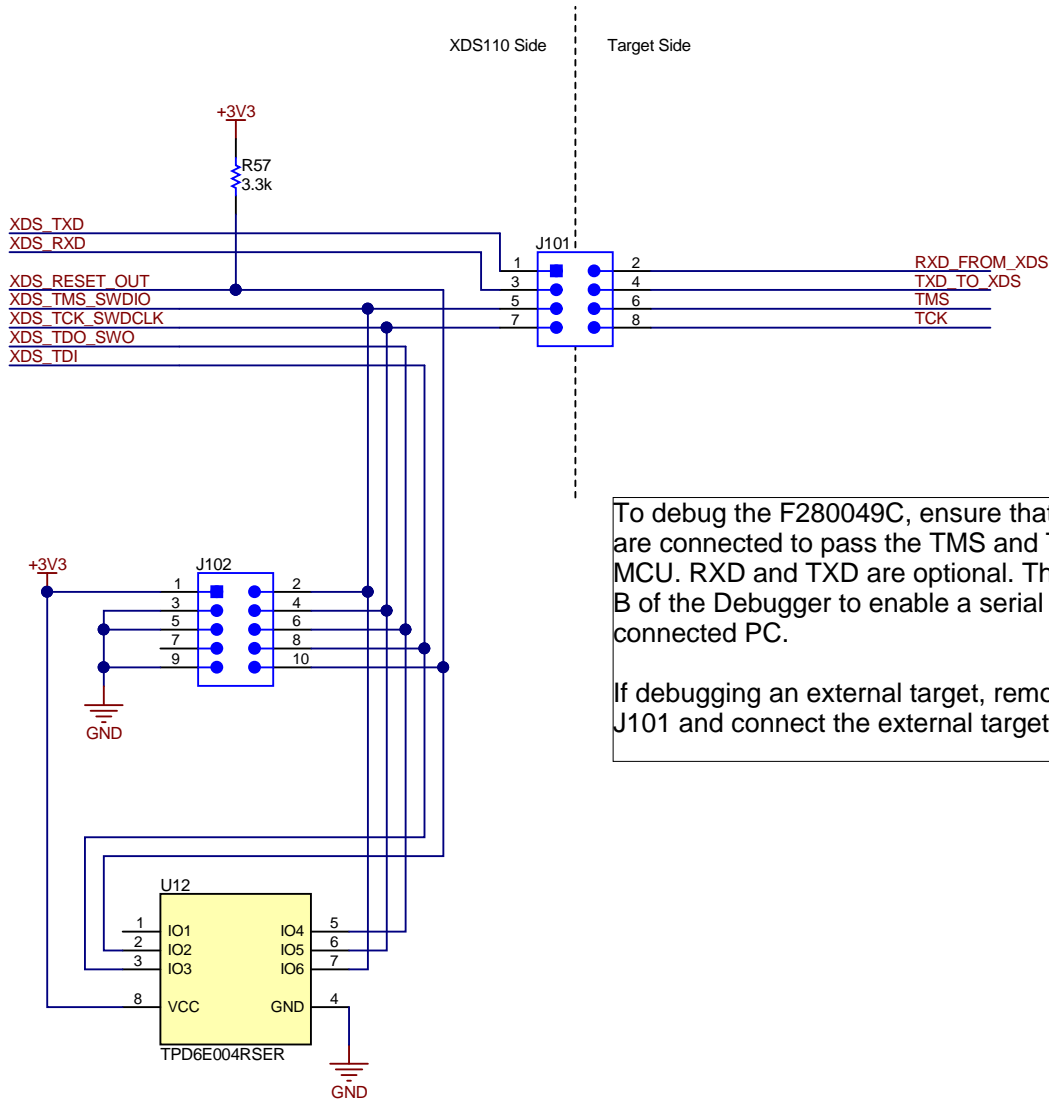
FSI and CAN Routing



If needed, depopulate the resistors to isolate the BP headers from the FSI Headers. By default all are connected.

FSI routing will be as clean as possible to FSI header. BP resistors will be branches with short stubs off of main branch to reduce noise on high speed lines

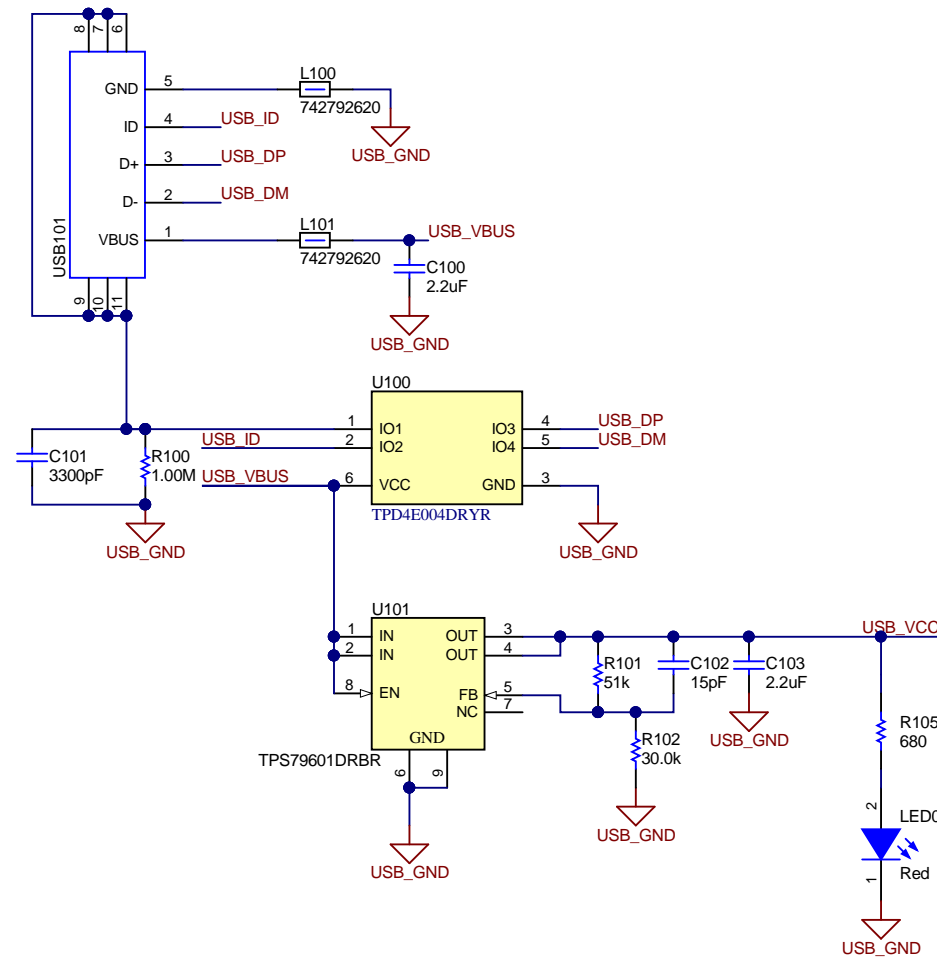
If CAN functionality is desired, ensure that R46 is populated with a 0-ohm resistor.



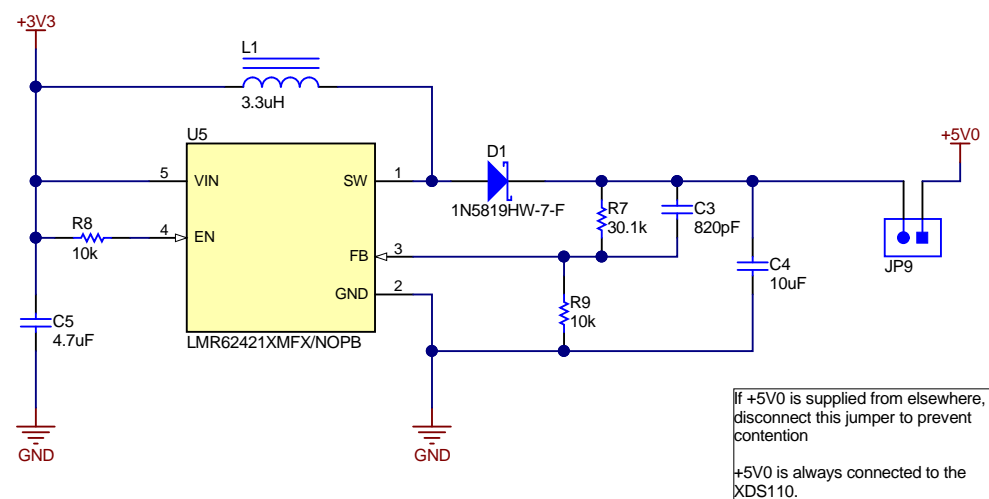
To debug the F280049C, ensure that the jumpers on J101 are connected to pass the TMS and TCK signals to the MCU. RXD and TXD are optional. These are for Channel B of the Debugger to enable a serial interface to the connected PC.

If debugging an external target, remove the jumpers from J101 and connect the external target to J102.

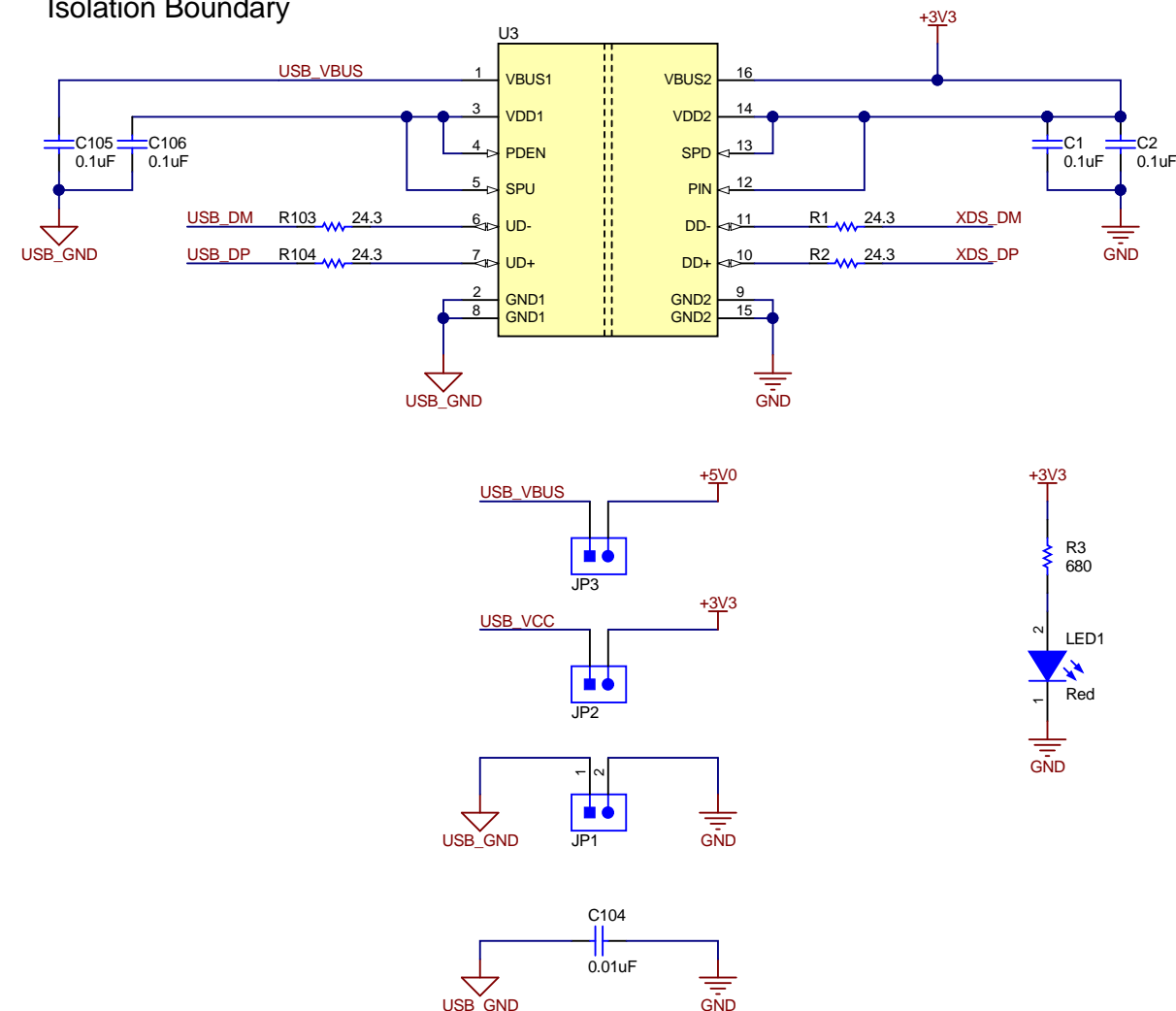
USB & XDS Power



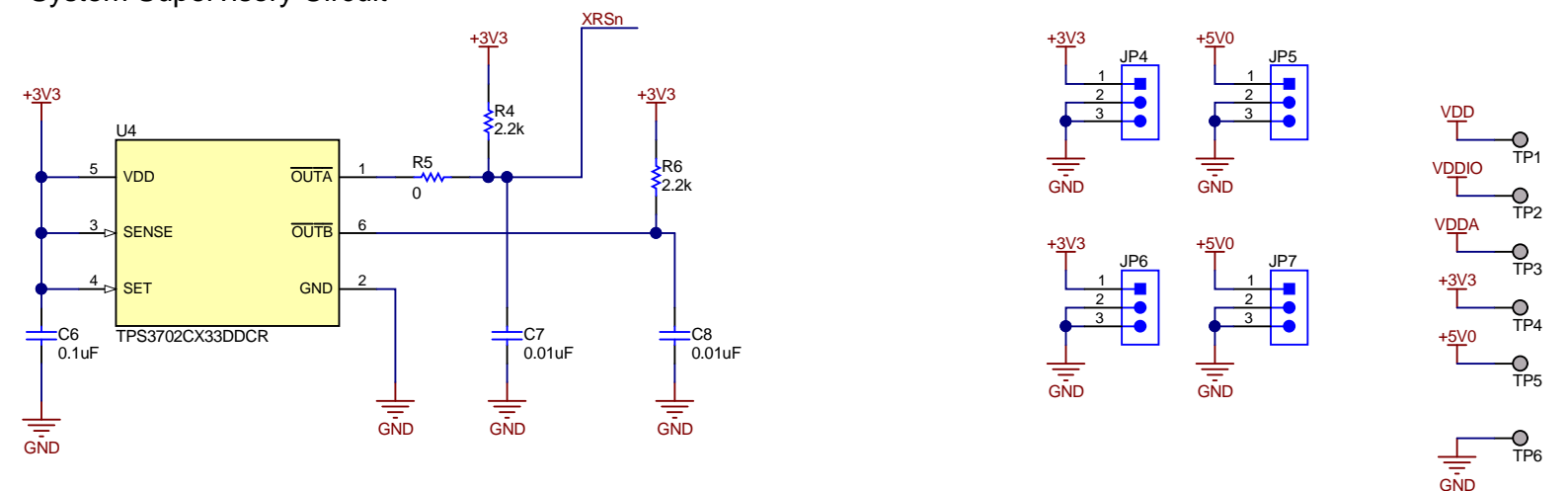
3.3V to 5V Boost




Isolation Boundary



System Supervisory Circuit



Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Orderable: LAUNCHXL-F280049C	Designed for: Public Release	Mod. Date: 11/18/2019	 TEXAS INSTRUMENTS http://www.ti.com © Texas Instruments 2019
TID #: N/A	Project Title: LAUNCHXL-F280049C		
Number: MCU025	Rev: B	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 6 of 8	
Drawn By:	File: MCU025B_XDS110_USB_Power.SchDoc	Size: B	
Engineer: a0232540	Contact: http://www.ti.com/support		

A

A

DNP FID1 DNP FID2 DNP FID3

DNP
FID2

DNP
FID3

DNP **DNP** **DNP**
FID4 FID5 FID6

DNP
FID5

DNP
FID6

M

MH2

M

MH4

PCB Number: MCU025
PCB Rev: B

Logo1
PCB
LOGO
Texas Instruments



CE Logo1

Logo4
PCB
LOGO
INSTASPIN_FOC_LOGO

Logo3
PCB
LOGO
FCC disclaimer

Logo2
PCB
LOGO
WEEE logo

H1
MECH
AK67421-0.3

Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note


These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Texas Instruments and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. Texas Instruments and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. Texas Instruments and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

Orderable: LAUNCHXL-F280049C	Designed for: Public Release	Mod. Date: 11/19/2019	
TID #: N/A	Project Title: LAUNCHXL-F280049C		
Number: MUC025	Rev: B	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: 001	Sheet: 8 of 8	
Drawn By:	File: MUC025B_Hardware.SchDoc	Size: B	
Engineer: a0232540	Contact: http://www.ti.com/support		http://www.ti.com © Texas Instruments 2019